



Attorney Docket: 501010.20522  
Today's Date: October 25, 2002  
Serial No. 10/045,651  
Filing Date: November 7, 2001  
For: MULTI-LAYER PRINTED CIRCUIT BOARD FABRICATION  
SYSTEM AND METHOD

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FIRST CLASS MAILING CERTIFICATE

FIRST CLASS MAIL

**Deposited: October 25, 2002**

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*William H. Dippert*  
William H. Dippert  
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